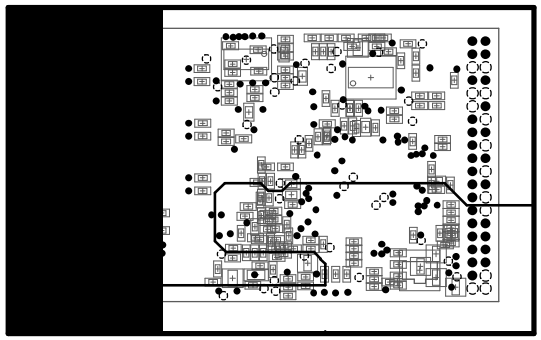
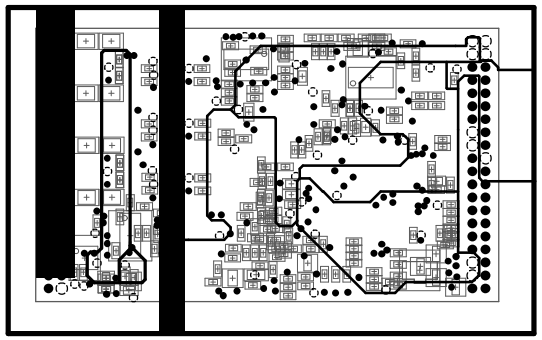


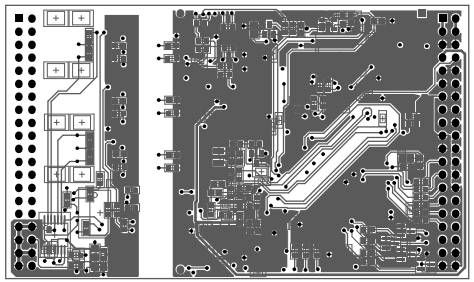
TOP



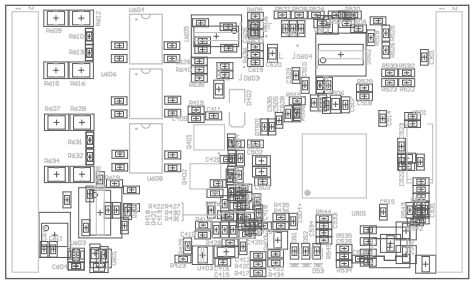
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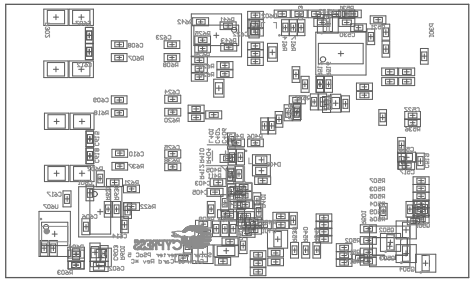
POWER



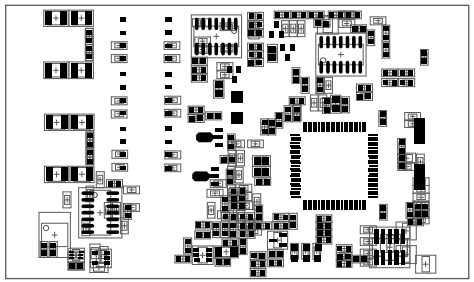
BOTTOM



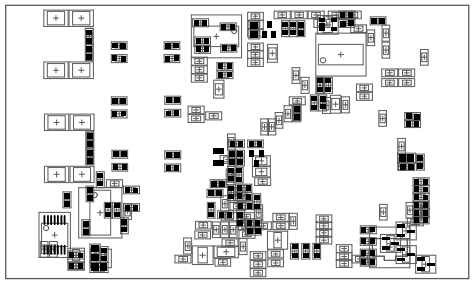
TOP SILKSCREEN



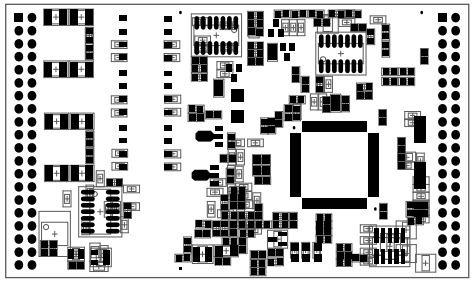
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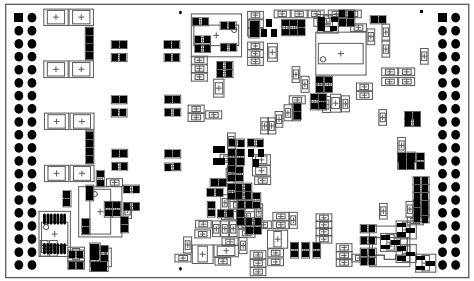
TOP PASTE



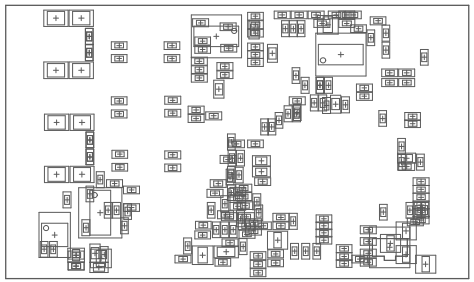
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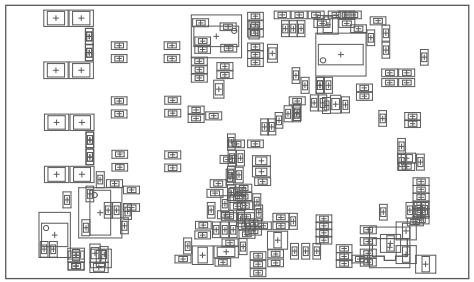


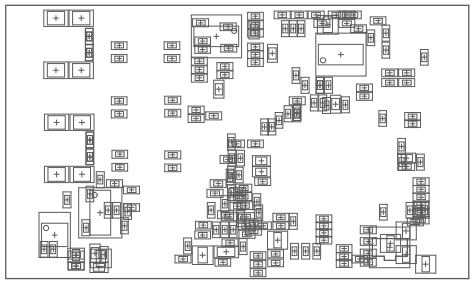
TOP SOLDER

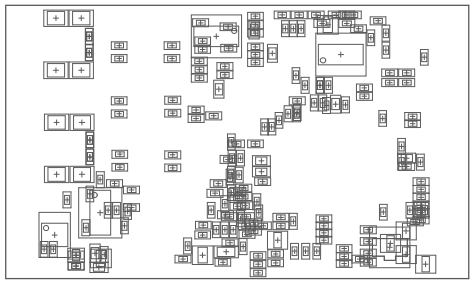


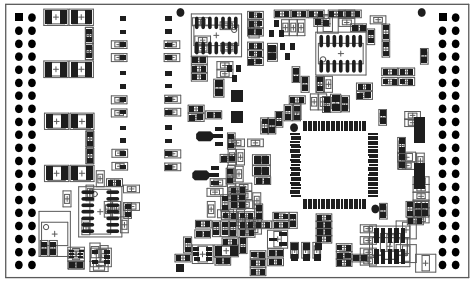
BOTTOM SOLDER

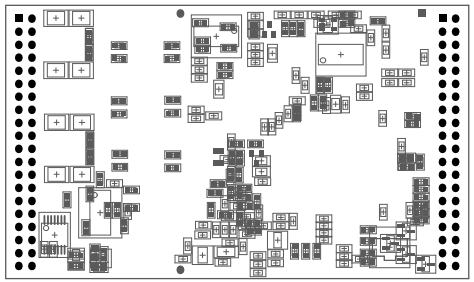


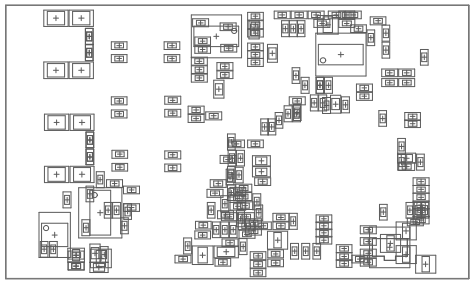












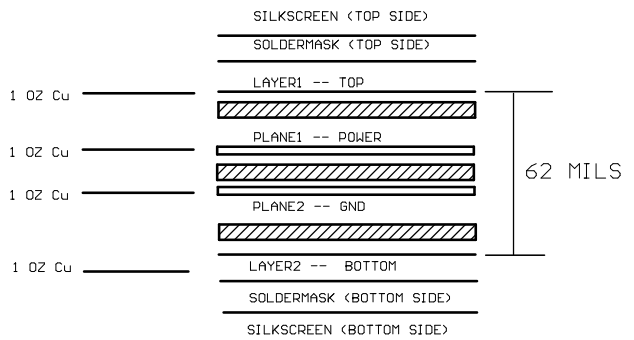
KEEP-OUT

NOTES: (UNLESS OTHERWISE SPECIFIED)

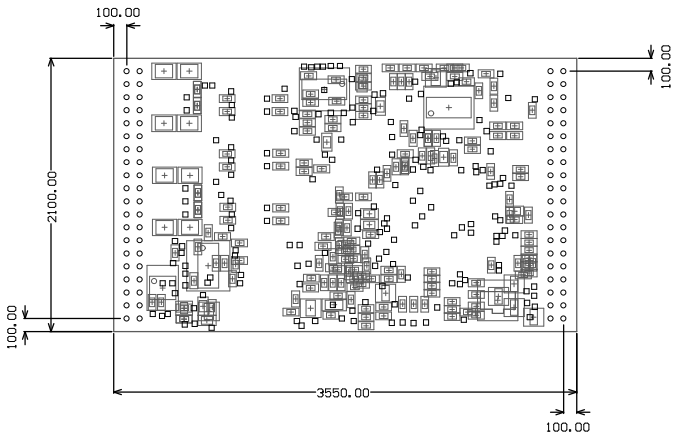
1. FABRICATE AS PER IPC-6012A TYPE2,CLASS2.
2. BOARD MATERIAL:FR4
3. BOARD FINISH:IMMERSION GOLD.
4. BOARD THICKNESS:62 MILS +/-5 MIL TOL.
5. APPLY SOLDER MASK ON BOTH SIDES USING LPI PROCESS,COLOR:BLUE/GREEN
6. APPLY SILKSCREEN LEGEND USING WHITE NON CONDUCTIVE EPOXY INK.
7. WARP AND TWIST SHOULD NOT EXCEED .005 INCH PER INCH IN ANY DIRECTION.
8. DIMENSIONAL LIMITS APPLY AFTER PLATING OR COATING.
9. MINIMUM PLATING ON ALL THE THROUGH HOLE SHALL BE 0.001 Cu.
10. NO VENDOR LOGO OR NAME ON THE BOARD
11. BOARD DIMENSIONS ARE IN MIL.
12. CLIP THE SILKSCREEN OVER SOLDERMASK
13. BOARD MUST BE FREE FROM VOIDS, PITS, SCRATCHES AND RESIDUE SUCH AS DIRT, GREASE ETC.
14. ALL MATERIAL USED MUST BE ROHS COMPLIANT
15. PCB VENDOR MUST NOTIFY RESPONSIBLE CYPRESS CONTACT OF ANY DISCREPANCIES BETWEEN FABRICATION DATA AND FABRICATION DRAWING
15. SMOOTHEN ALL ROUGH EDGES

REVISIONS	DATE
REV **	APR 2012
REV *A	JUN 2012
REV *B	NOV 2012
REV *C	MAY 2013

LAYER STACKUP - 4 LAYER



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	173	15mil (0.381mm)	PTH	Round
○	80	35.433mil (0.9mm)	PTH	Round
	253 Total			



LAYER FAB

CYPRESS SEMICONDUCTOR CORPORATION

198 CHAMPION CT, SAN JOSE, CA 95134

TITLE:	PSoC 5LP - SOLAR MICROINVERTER CONTROL CARD		
DRAWN BY	DATED	Drill Drawing.	REV
SNVN	MAY 2013	FILM LAYERS ARE SHOWN AS VIEWED FROM THE TOP SIDE OF THE BOARD.	*C
		UNITS: MIL	SIZE A3

